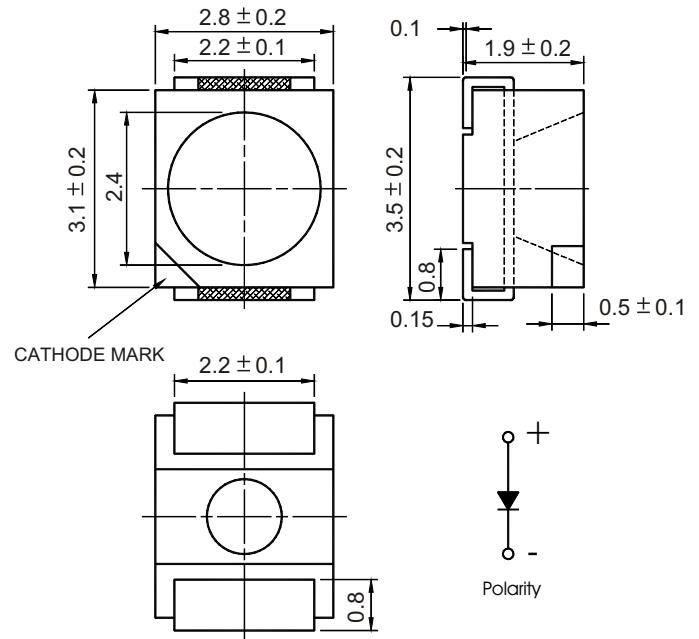




● Features:

- 1. Chip material: InGaN/SiC
- 2. Emitting color: Ultra White
- 3. Lens Appearance: Water Clear
- 4. Long life-solid state reliability
- 5. Compatible with automatic placement equipment
- 6. Compatible with reflow solder process
- 7. RoHS compliant

● Package dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25\text{mm}$ ($0.01''$) unless otherwise specified.
- 3. Specifications are subject to change without notice.



● Absolute maximum ratings ($T_a=25^\circ\text{C}$)

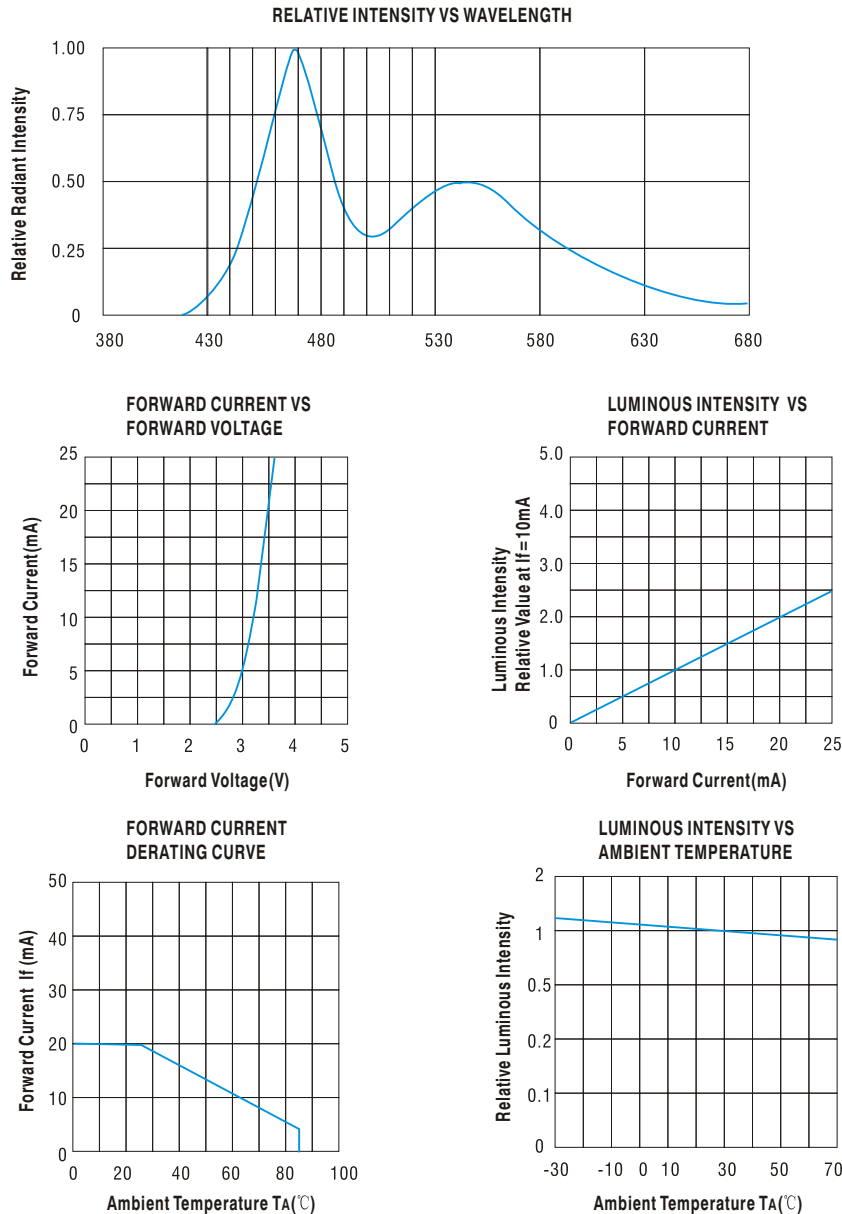
| Characteristic | Test Condition | Symbol | UW | Units |
|----------------------------|------------------------------------|-----------|------------|------------------|
| Pulse Forward Current | 1/10 duty cycle 0.1ms Pulse width | I_{FP} | 100 | mA |
| DC Forward Current | | I_F | 20 | mA |
| Reverse Current | $V_R=5V$ | I_R | 10 | μA |
| Power Dissipation | | P_D | 120 | mW |
| Operating Temperature | | T_{OPR} | -40 to +80 | $^\circ\text{C}$ |
| Storage Temperature | | T_{STG} | -40 to +85 | $^\circ\text{C}$ |
| Lead Soldering Temperature | 1.60mm from body maximum 3 seconds | T_{SOL} | 260 | $^\circ\text{C}$ |



● Electrical And Optical Characteristics(Ta=25°C)

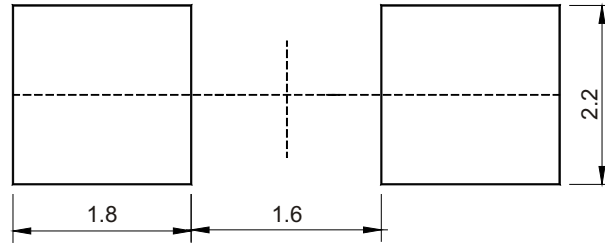
| Parameter | Test Condition | Symbol | Min. | Typ. | Max. | Units |
|--------------------------|--------------------|----------------|------|------|------|-------|
| Forward Voltage | IF=20mA | V _F | --- | 3.30 | 3.80 | V |
| Reverse Current | V _R =5V | I _R | --- | --- | 10 | μA |
| Chromaticity Coordinates | IF=20mA | X | --- | 0.30 | --- | nm |
| | | Y | --- | 0.31 | --- | nm |
| Spectral Line Half-width | IF=20mA | Δλ | --- | --- | --- | nm |
| Luminous Intensity | IF=20mA | I _V | --- | 1200 | --- | mcd |
| Viewing Angle | IF=20mA | 2θ½ | --- | 120 | --- | deg. |

● Typical electro-optical characteristics curves





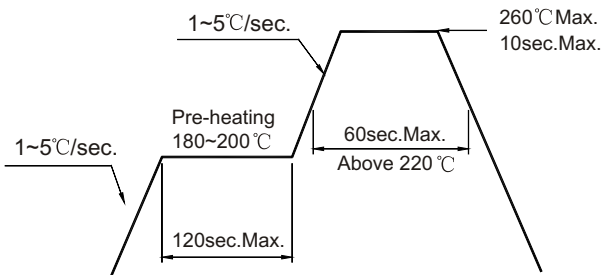
● Soldering Pad Dimensions:



● Soldering Conditions:

1. Reflow soldering profile

Lead-free solder



2. Soldering Iron

Power dissipation of iron should be smaller than 25W, and temperature should be controllable. The work must be finished within 3sec. under 300°C only once.

Do not stress its resin while soldering.

After soldering, do not warp the circuit board.

● Package Tape Specifications:(1000~2000pcs/Reel)

